

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S6	1039	257/698.ccls.	US-PGPUB; USPAT	OR	ON	2005/02/07 11:11
S7	164	S6 and (heat adj sink)	US-PGPUB; USPAT	OR	ON	2005/02/07 10:58
S8	1083	257/700.ccls.	US-PGPUB; USPAT	OR	ON	2005/02/07 11:11
S9	172	S8 and (heat adj sink)	US-PGPUB; USPAT	OR	ON	2005/02/07 11:11
S12	13	((("5014419") or ("5380681") or ("5432999") or ("5770476") or ("5869891") or ("5880024") or ("5908304") or ("5963795") or ("5973392") or ("6002177") or ("6020629") or ("6137163") or ("6188127"))).PN.	US-PGPUB; USPAT	OR	OFF	2005/02/07 11:23
S13	1	("6780672").PN.	US-PGPUB; USPAT	OR	OFF	2005/02/07 11:26
S14	1	("20030022417").PN.	US-PGPUB; USPAT	OR	OFF	2005/02/07 12:27
S15	70	(heat adj sink) with copper with tungsten with alloy	US-PGPUB; USPAT	OR	ON	2005/02/07 12:28
S17	154	package and heat\$1sink and (substrate with opening)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/26 14:49
S18	25	S17 and (heat\$1sink with substrate with opening)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/26 15:35
S19	2286	(257/706.ccls. 257/712.ccls. 257/720.ccls.) not (257/E23.141.ccls. 257/E23.174.ccls. 257/E23.169.ccls. 257/698.ccls. 257/700.ccls.)	US-PGPUB; USPAT	OR	ON	2005/04/27 11:27
S20	4490	packag\$5 and optoelectronic	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/27 11:28

S21	326	S20 and electroplat\$5	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/27 11:28
S22	159	S21 and (nickel Ni) and (gold Au)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/27 11:33
S23	47	S22 and pins	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/27 11:33
S24	20	"5014904"	US-PGPUB; USPAT	OR	ON	2005/05/27 17:49
S25	0	heat\$1sink with (copper adj tungsen adj alloy)	US-PGPUB; USPAT	OR	ON	2005/05/27 17:49
S26	326830	heat\$1sink with copper with tungsen wiht alloy	US-PGPUB; USPAT	OR	ON	2005/05/27 17:50
S27	0	heat\$1sink with copper with tungsen with alloy	US-PGPUB; USPAT	OR	ON	2005/05/27 17:50
S28	0	heat\$1sink with copper with tungsen	US-PGPUB; USPAT	OR	ON	2005/05/27 17:50
S29	18	heat\$1sink with copper with tungsten with alloy	US-PGPUB; USPAT	OR	ON	2005/05/27 18:49
S30	512	(ceramic with substrate) with plat\$5 with gold	US-PGPUB; USPAT	OR	ON	2005/05/27 18:49
S32	152	S30 with nickel	US-PGPUB; USPAT	OR	ON	2005/05/27 19:38
S33	1	heat\$1sink with braz\$5 with copper with silver with alloy	US-PGPUB; USPAT	OR	ON	2005/05/27 19:58
S34	0	braz\$5 with copper with silver with alloy with (strong\$3 better best) with adhesive	US-PGPUB; USPAT	OR	ON	2005/05/27 19:59
S35	14	braz\$5 with copper with silver with alloy with (strong\$3 better best)	US-PGPUB; USPAT	OR	ON	2005/05/27 19:59
S36	132	plating with (silver and gold) with electrolytic\$5	US-PGPUB; USPAT	OR	ON	2005/05/27 21:02